12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251210000.1A
Qualification of RFAB using qualified Process Technology, Datasheet, Die revision, additional Assembly site and BOM options for select devices

Change Notification / Sample Request

The rev A is being issued to clarify the the mentioned UTL sites.

Date: March 04, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20251210000.1A
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AVC4T245RSVR	SN74AVC4T245RSVR
SN74AVC4T774RSVR	NULL
SN74AVCH4T245RSVR	NULL
74AVC4T774RSVRG4	NULL
74AVCH4T245RSVR-NT	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251210000.1A	PCN Date:	March 04, 2026
Title:	Qualification of RFAB using qualified Process Technology, Datasheet, Die revision, additional Assembly site and BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	June 02, 2026	Sample requests accepted until:	May 03, 2026*

***Sample requests received after May 03, 2026 will not be supported.**

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB as an additional Wafer Fab option for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
FFAB	ASLC10	200 mm	RFAB	LBC7	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1

	Current Site		Additional Site
Assembly	ATXSZ	UTL1	**CDAT**
Wire diam/type	Au; 0.8 mil	Au; 0.6 mil	Cu; 0.8 mil
Mold Compound	SID#1801512111	SID#CZ0136	4222198
Mount Compound	SID#1400238112	SID#PZ0037	4221460 4226215
Tape width	12.4	12.4	8.4

Group 2

	Current Site	New
Assembly	UTL1	**UTL3**
Wire diam/type	Au; 0.6 mil	Cu; 0.8 mil
Mold Compound	SID#CZ0136	SID#CZ0297
Mount Compound	SID#PZ0037	SID#PZ0076
Tape width	12.4	8.4

The product datasheet(s) is updated as seen in the change revision history below:

TEXAS INSTRUMENTS

SN74AVC4T774

SCES693I – FEBRUARY 2008 – REVISED FEBRUARY 2025

Changes from Revision H (May 2024) to Revision I (February 2025)	Page
• Updated RGY and PW thermal information	7

TEXAS INSTRUMENTS

SN74AVCH4T245

SCES577F – JUNE 2004 – REVISED FEBRUARY 2025

Changes from Revision E (November 2015) to Revision F (February 2025) **Page**

- Updated PW and RGY *Thermal Information* 8

Changes from Revision H (March 2024) to Revision I (February 2025) **Page**

- Updated PW and RGY thermal information..... 8

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74AVC4T774	SCES693H	SCES693I	http://www.ti.com/product/SN74AVC4T774
SN74AVCH4T245	SCES577E	SCES577F	http://www.ti.com/product/SN74AVCH4T245
SN74AVC4T245	SCES576H	SCES576I	http://www.ti.com/product/SN74AVC4T245

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None; see the standard data package for complete details.

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TIB	DEU	Freising
RFB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
-	**B**

Assembly Site Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
ATXSZ	ASN	CHN	Suzhou
UTL1	NSE	THA	Bangkok
UTL3	UT3	THA	Bangpakong
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label):

Product Affected: Group 1

SN74AVC4T245RSVR	SN74AVC4T774RSVR	74AVC4T245RSVR-NT	74AVC4T774RSVR-NT
SN74AVCH4T245RSVR	74AVCH4T245RSVR-NT	74AVC4T245RSVRG4	74AVC4T774RSVRG4

Product Affected: Group 2

SN74AVC4T245RSVR	SN74AVC4T774RSVR	HPA00719RSVR	

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC4T245RSVR	Qual Device: SN74AVC4T774RSVR	Qual Device: SN74AVCH4T245RSVR	QBS Reference: SN3257QDYYRQ1	QBS Reference: PTMUXHS221NKGR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	1/77/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	-	3/2400/0	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC4T245RSVR	Qual Device: SN74AVC4T774RSVR	Qual Device: SN74AVCH4T245RSVR	QBS Reference: SN3257QDYYRQ1	QBS Reference: PTMUXHS221NKGR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	1/5/0	-	-	3/30/0	3/15/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	3/9/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	1/3/0	3/9/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	1/6/0	3/18/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	3/90/0	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74AVC4T245RSVR is qualified at MSL1 260C
- Qual Device SN74AVC4T774RSVR is qualified at MSL1 260C
- Qual Device SN74AVCH4T245RSVR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2410-073

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC4T245RSVR	Qual Device: SN74AVC4T774RSVR	ProcessQBS Reference: SN3257QDYYRQ1	Package QBS Reference: TPS62261DRVR	Product QBS Reference: SN74AVC4T245RSVR	Package QBS Reference: TCAN1042VDRBRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	3/231/0	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	-	3/135/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	1/77/0	-	-	-	1/77/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	3/66/0	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC4T245RSVR	Qual Device: SN74AVC4T774RSVR	ProcessQBS Reference: SN3257QDYYRQ1	Package QBS Reference: TPS62261DRVR	Product QBS Reference: SN74AVC4T245RSVR	Package QBS Reference: TCAN1042VDRBRQ1
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/6/0	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	3/90/0	1/30/0	1/30/0	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74AVC4T245RSVR is qualified at MSL1 260C
- Qual Device SN74AVC4T774RSVR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-061

For alternate parts with similar or improved performance, please visit the product page on TI.com

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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